ENVIRONMENTAL AND PACKAGE TESTING DATA FOR MLP/QFN					
Stress	**Sample Size**	**Device Hr./Cyc**	**Condition**	**Total Fails**	**Fail Percentage**
85/85	165	51,700	85°C, 85%RH	0	0.00
BOND INT	960	700,000	200°C + N2	0	0.00
HAST	1,910	191,000	130°C, 85%RH	0	0.00
Pressure Pot	2,440	234,240	121°, 15 PSIG	0	0.00
Solder DUNK	425	1,275	260°C, 10SEC	0	0.00
Solderability	435	3,480	883 M2003	0	0.00
Temp Cycle	2,440	1,298,750	−65°C−150°C	0	0.00